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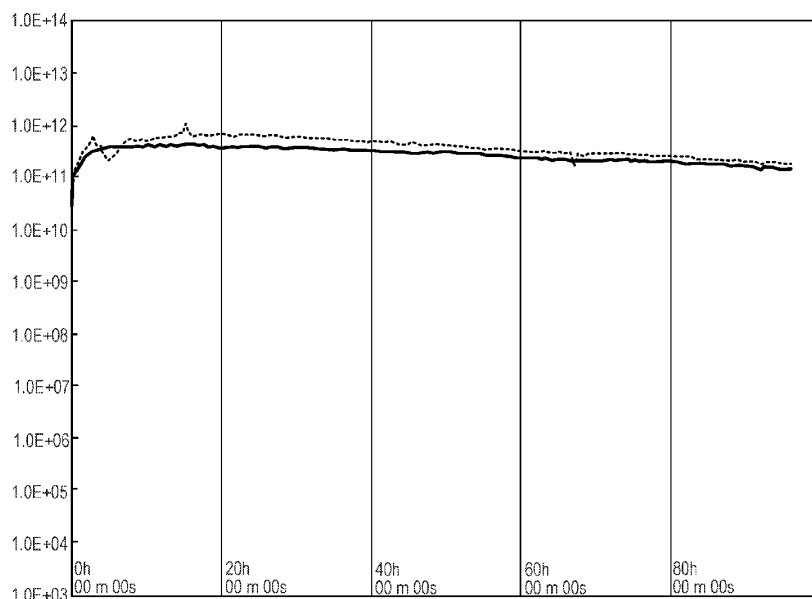


FIG. 1

(57) Abstract: The present disclosure generally relates to microelectronic devices with good reliability and related compositions and methods. In some embodiments, the methods include providing a composition comprising a hydrophobic multifunctional (meth)acrylate crosslinker and a polymer, and reacting the composition to provide a dielectric layer, wherein, when the dielectric layer is present in a microelectronic device, the microelectronic device exhibits good reliability. In certain embodiments, the compositions include a fully imidized polyimide and a hydrophobic multifunctional (meth)acrylate crosslinker, wherein the dielectric composition is suitable to provide a dielectric layer that imparts good reliability to a microelectronic device when the dielectric layer is present in the device.

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